



PANDA FEE Electronics



Sezione di Torino

MVD readout status report

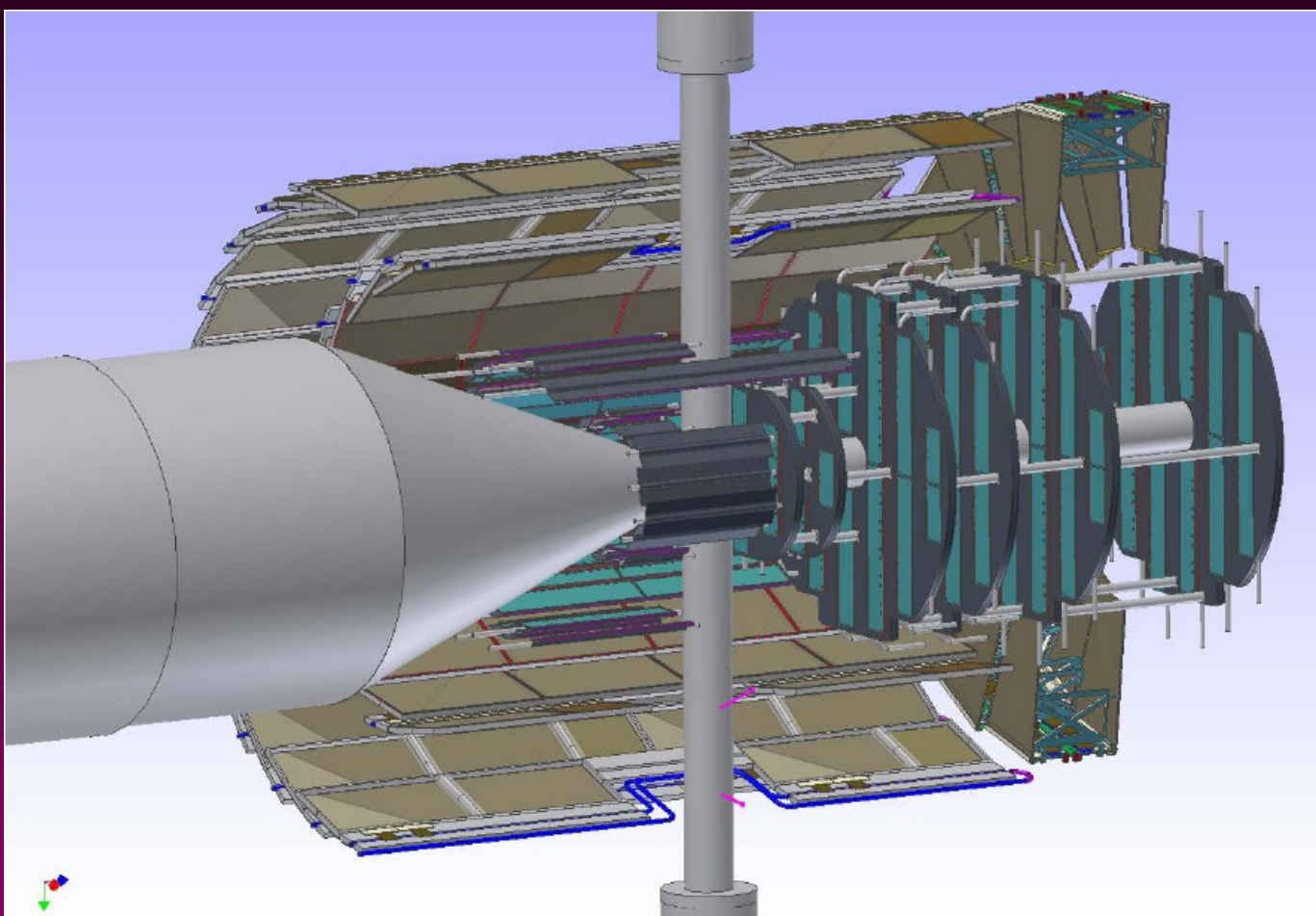
G. Mazza
on behalf of the MVD group



PANDA MVD



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* Barrel :

Layer 1 : radius 28 mm, SPDs

Layer 2 : radius 53 mm, SPDs

Layer 3 : radius 92 mm, SSDs

Layer 4 : radius 120 mm, SSDs

* Forward :

Disks 1-2 : radius 37.5 mm,
SPDs

Disks 3-4 : radius 75 mm, SPDs

Disks 5-6 : radius 130 mm,
SPDs + SSDs

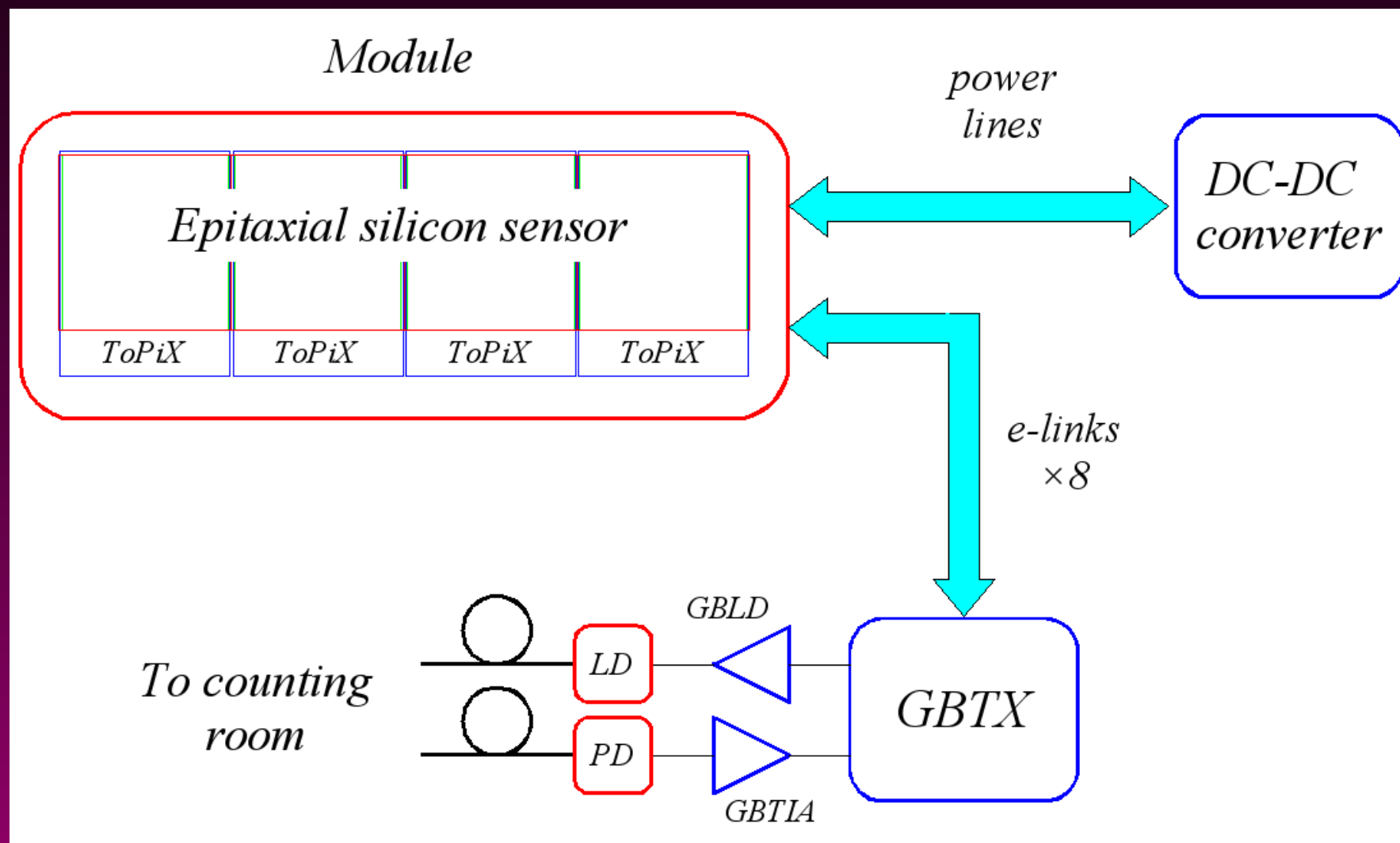


Pixel Detector



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<i>Pixel size</i>	$100 \times 100 \mu\text{m}^2$
<i>Chip active area</i>	$11.4 \times 11.6 \text{ mm}^2$ (116 rows, 110 cols)
<i>dE/dx measurement</i>	ToT, 12 bits dynamic range
<i>Max input charge</i>	50 fC
<i>Noise floor</i>	<32 aC (200 e^-)
<i>Input clock frequency</i>	155.52 MHz
<i>Time resolution</i>	6.43 ns (1.86 ns r.m.s.) 12.86 ns (3.71 ns r.m.s.)
<i>Power consumption</i>	< 800 mW/cm ²
<i>Max event rate</i>	$6.1 \cdot 10^6$
<i>Total ionizing dose</i>	< 100 kGy





ToPiX v3



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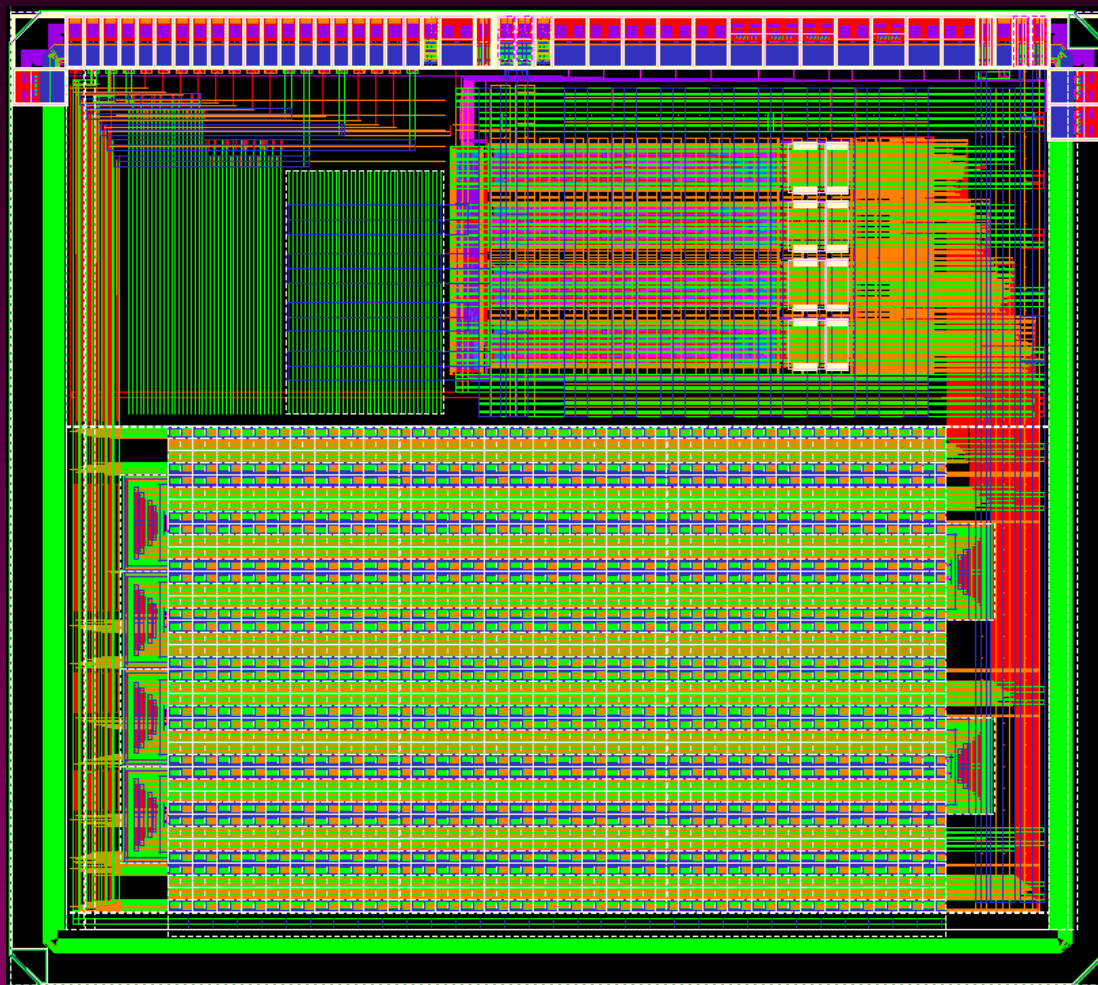
- Layout submitted on February 7th – received May 16th 2011
- 4.5x4 mm² die area
- CMOS 0.13 μm DM technology
- Triple redundancy-based SEU protection
- End of column logic
- 160 Mb/s SLVS serial output
- Pads for bump bonding



ToPiX v3 layout



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- * 4.5 mm × 4 mm
- * CMOS 130 nm
- * Clock frequency 160 MHz
- * bump bonding pads
- * 2×2×128 columns
- * 2×2×32 columns
- * 32 cells EoC FIFO
- * SEU protected EoC
- * Serial data output
- * SLVS I/O



ToPiX test results



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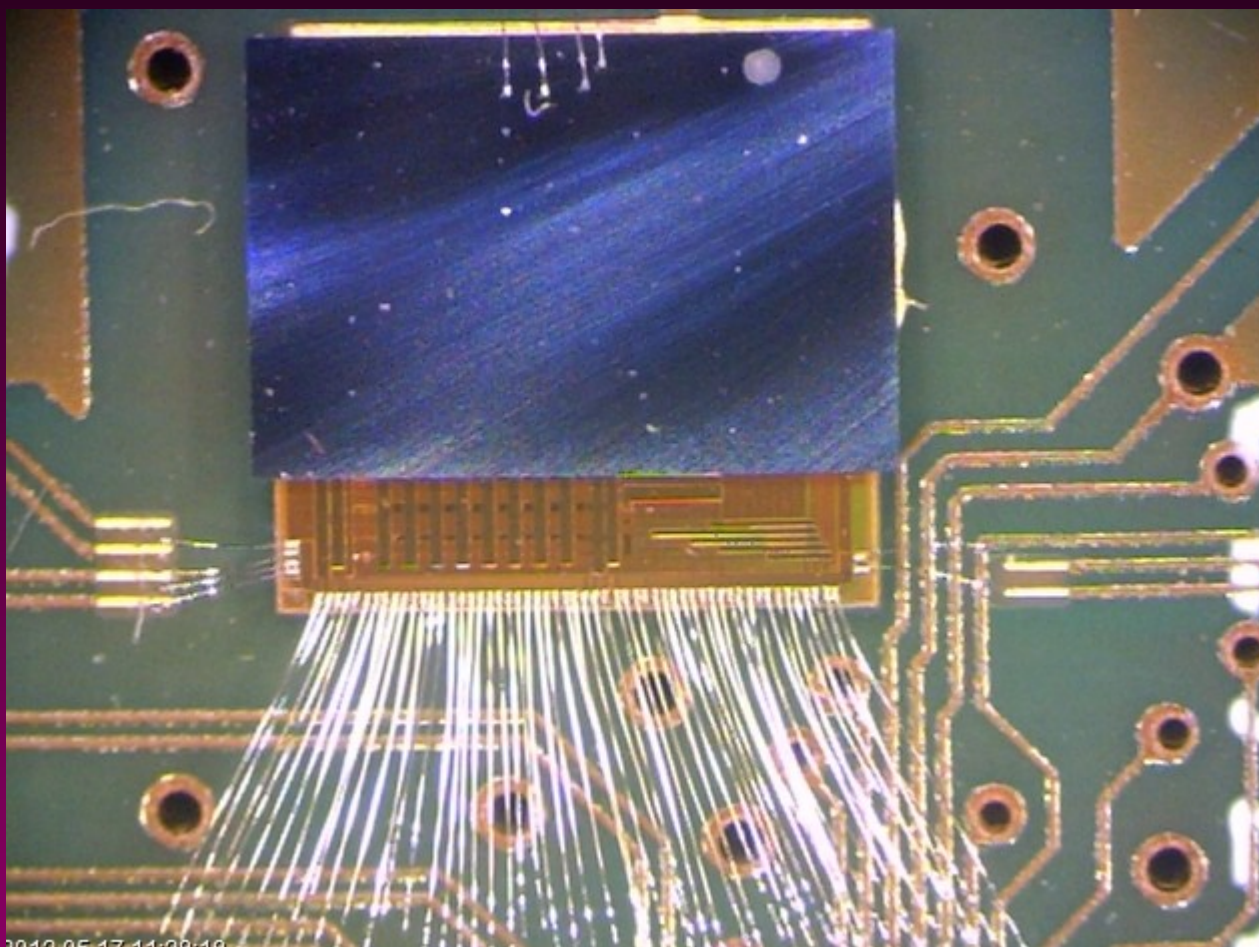
- * At 160MHz can only read and program first ~32 pixels of each column
- * At 50MHz (with pre-emphasis disabled) full operation
- * S-curve working well (programmable internal test pulse)
- * Baseline measurements ok
- * On-pixel DACs characterised and correction applied
- * Transfer function measurements in good agreement with simulations
- * Acquisition system is working (4 boards)
- * TID (@X ray-CERN) and SEU (@SIRAD-LNL) tests done

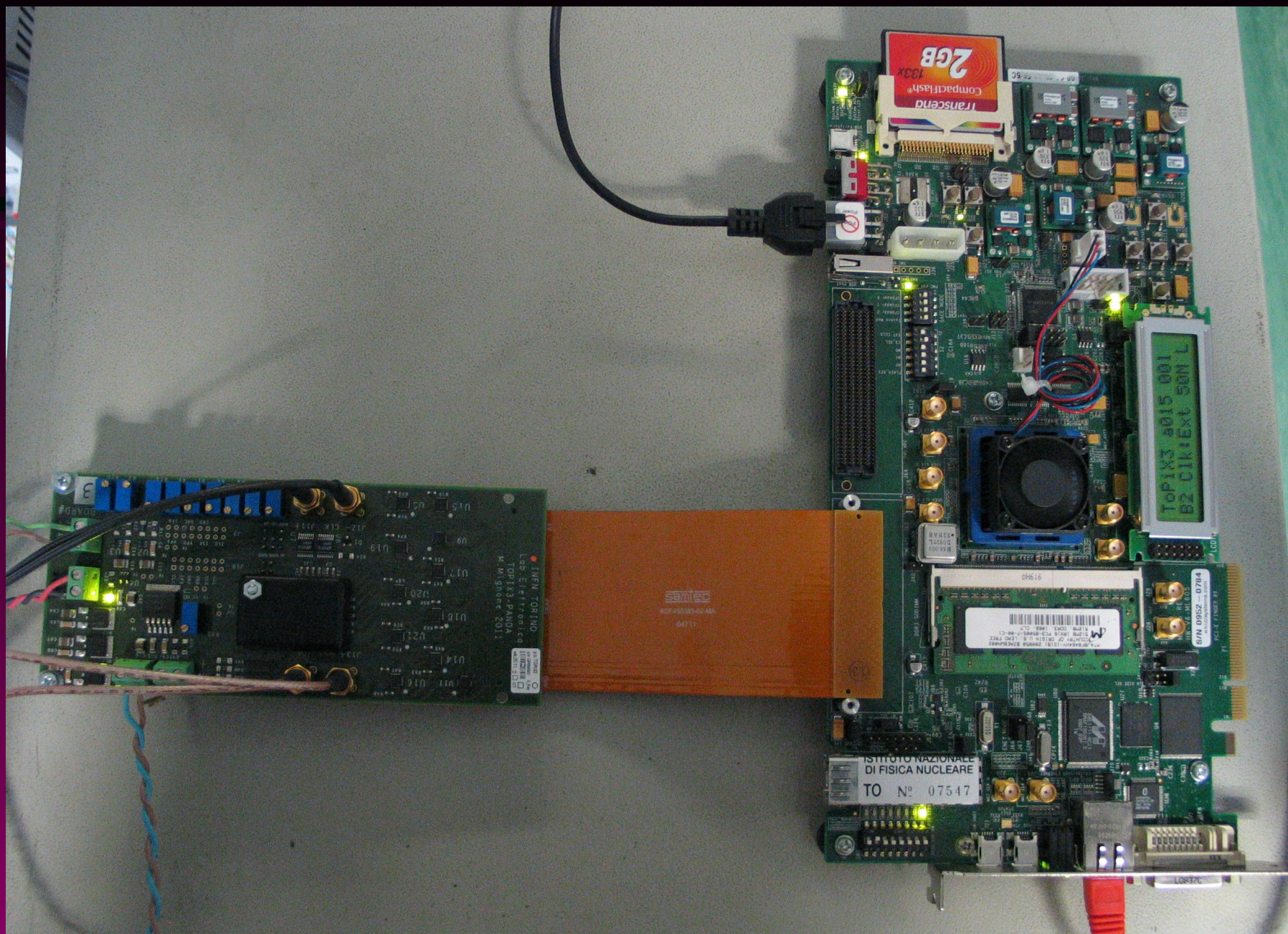


ToPiX + sensor



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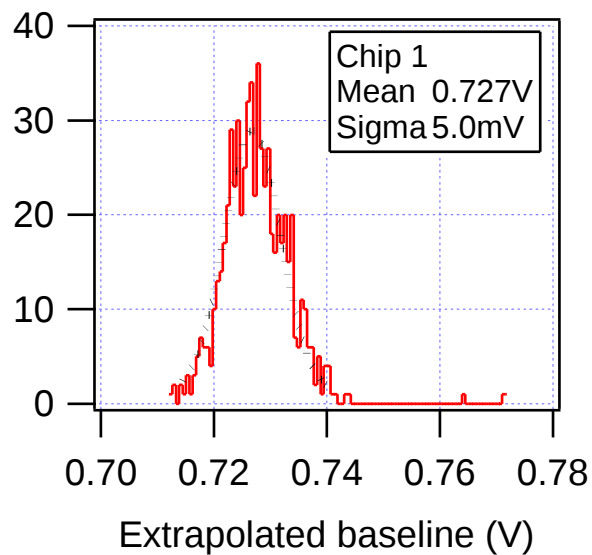
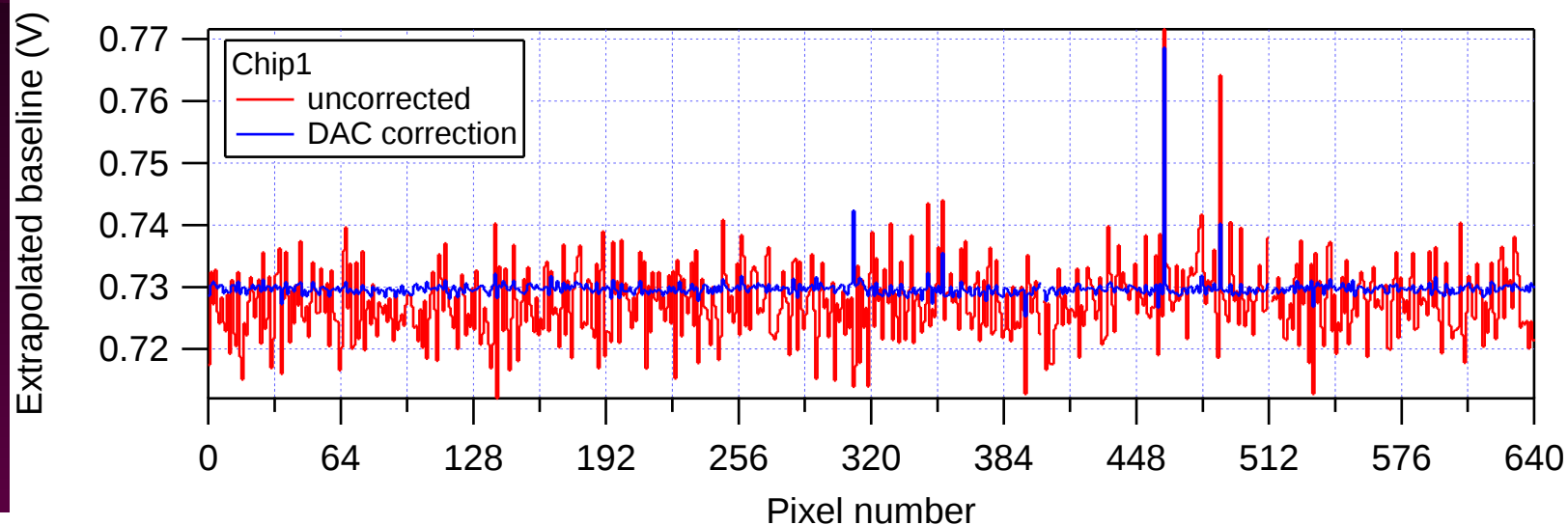




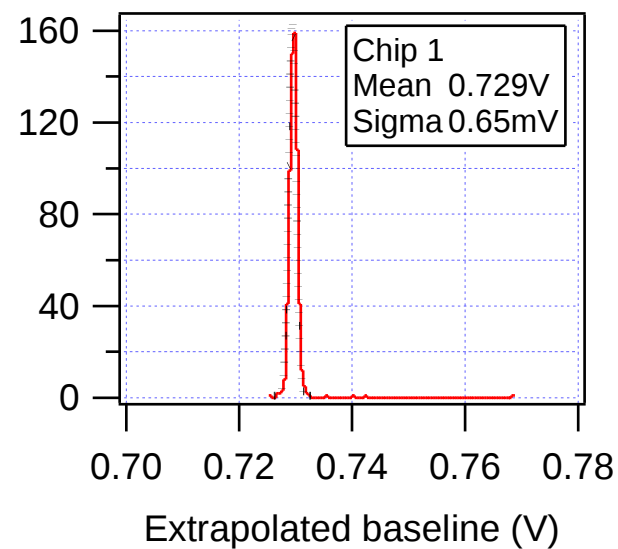
Baseline correction



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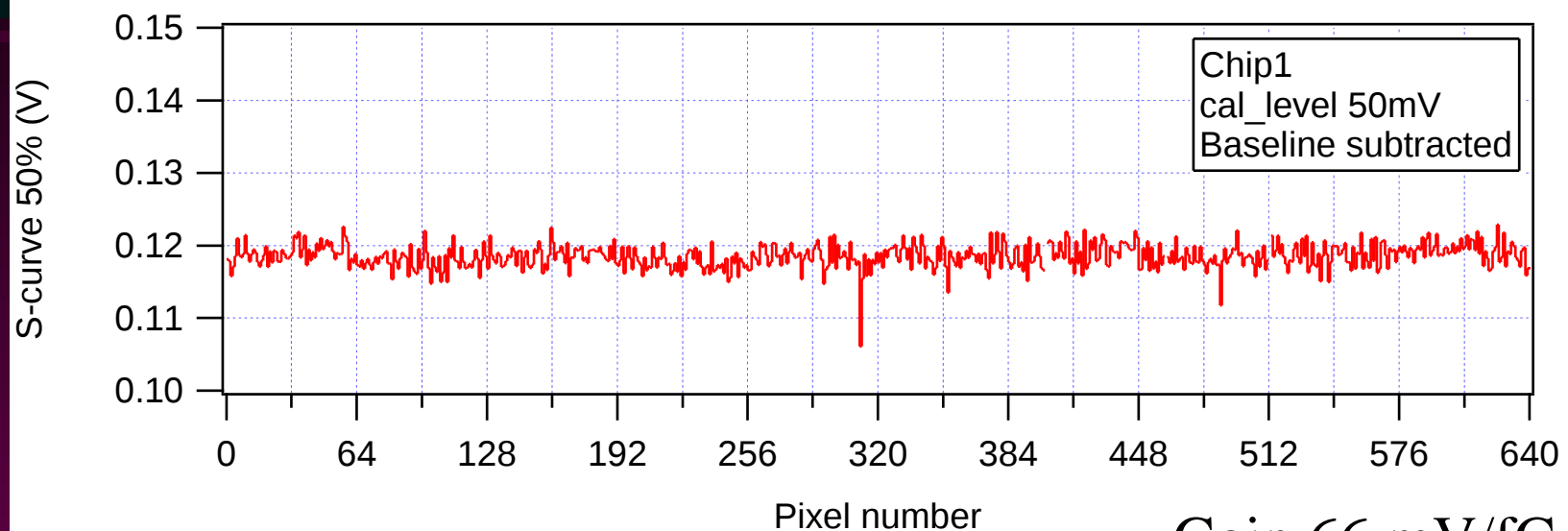


*DAC
correction*

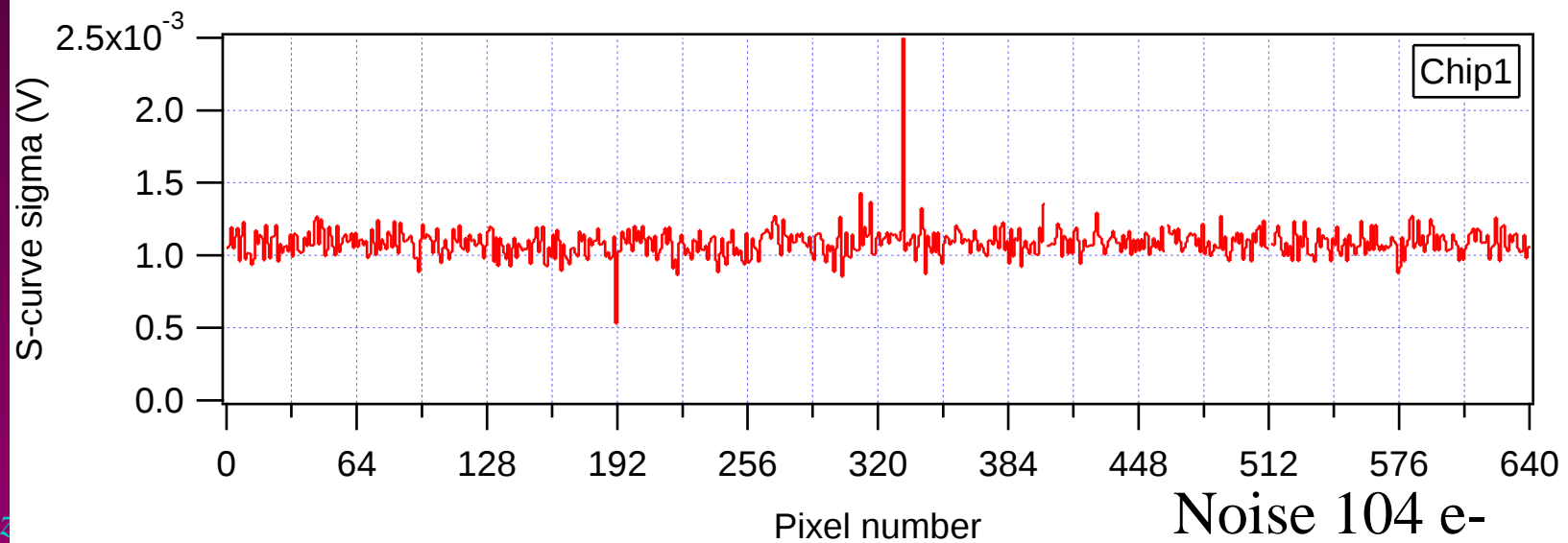




Gain & Noise



Gain 66 mV/fC

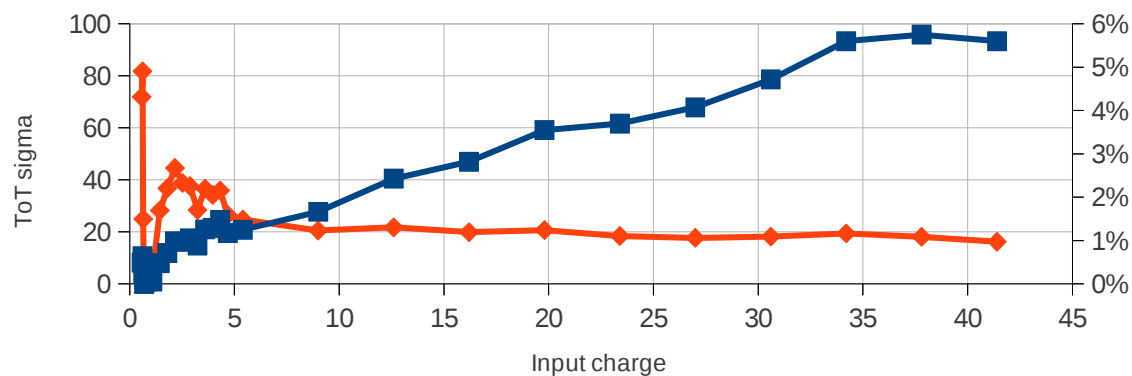
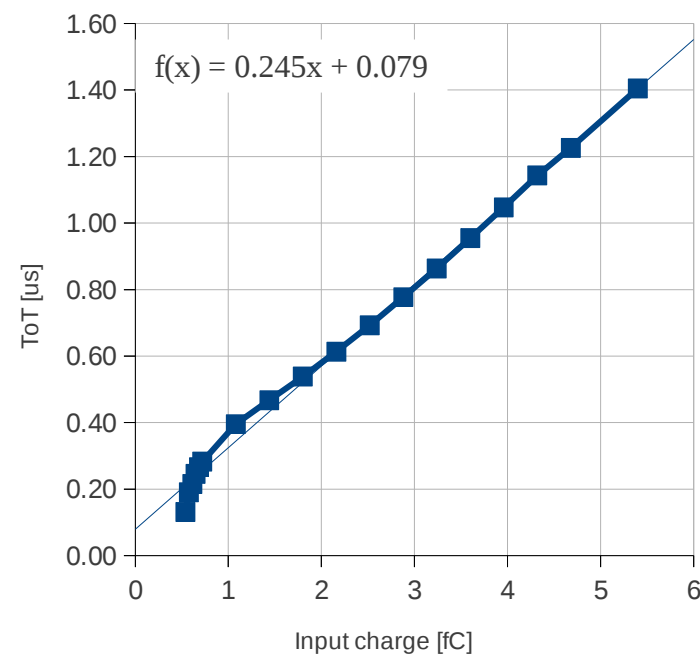
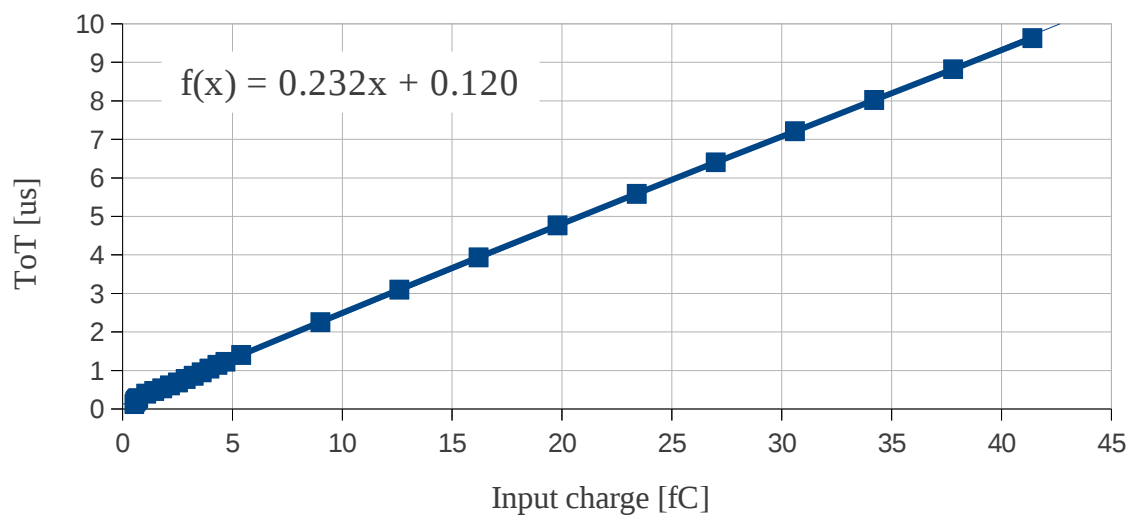




ToT @ 5 nA



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$$I_{FB} = 5 \text{ nA}$$

Simulated gain : 202 ns/fC



Open issues



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- * Clock frequency
- * Power consumption
- * Radiation tolerance
 - * TID effects
 - * SEU effects



Clock frequency problem



- * At 160 MHz only the columns with 32 double cells work correctly
- * Response improves when the frequency is decreased
- * “Easy” corrections :
 - * *Prototype full column has 30% longer bus and 10% more cells than the final chip*
 - * *Triple redundancy latches have been connected without buffers*
 - * *Buffers can serve two pixels*
 - * *Change in le readout timing – see next slide*
- * Bus estimated capacitance : 47.35 fF/cell (55% due to the cell, 45% due to interconnection capacitance)
- * Total bus capacitance per line : 6.88 pF (now), 2.98 pF (est.)



Timing issue

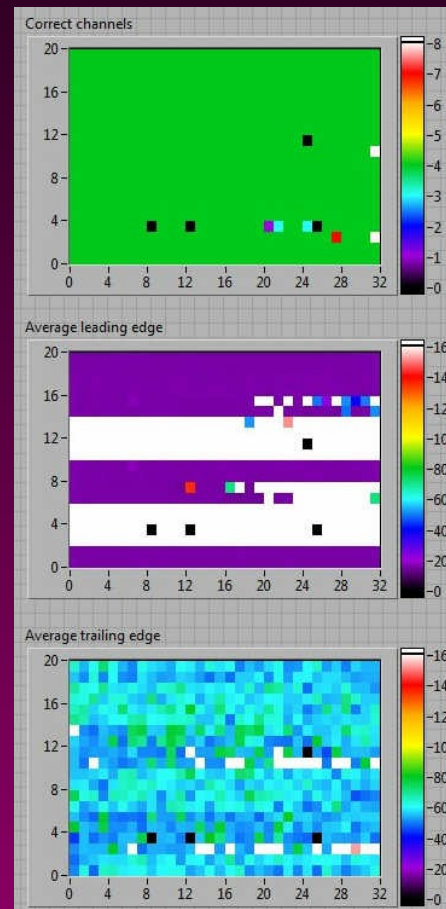
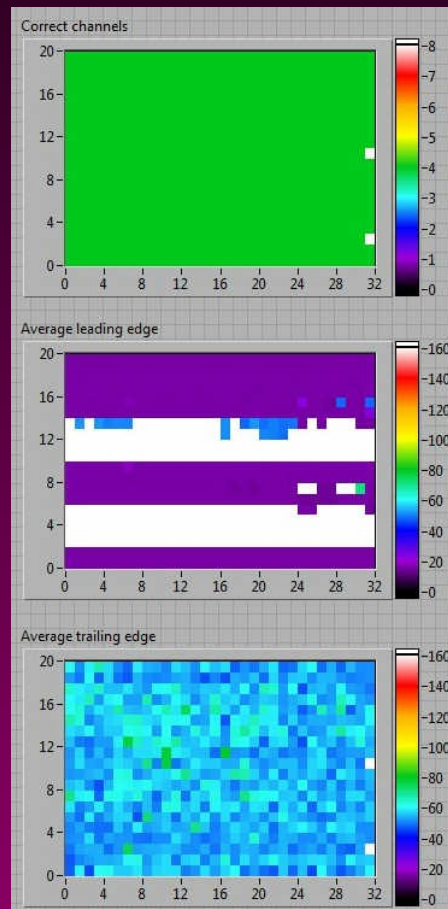
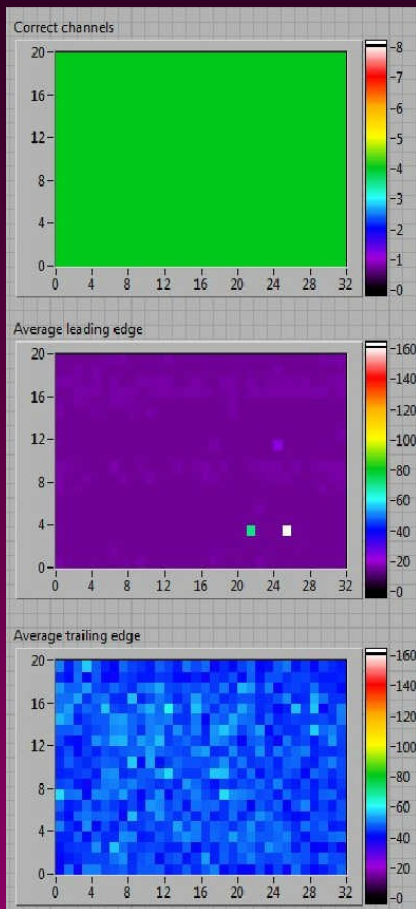


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50 MHz

65 MHz

70 MHz



- * Trailing edge still good @ 65 MHz
- * Read leading edge cmd asserted at the same time as read cmd.
- * Read trailing edge cmd asserted when read cmd is already high
- * Clock cycle to be inserted between read cmd and read leading edge cmd.



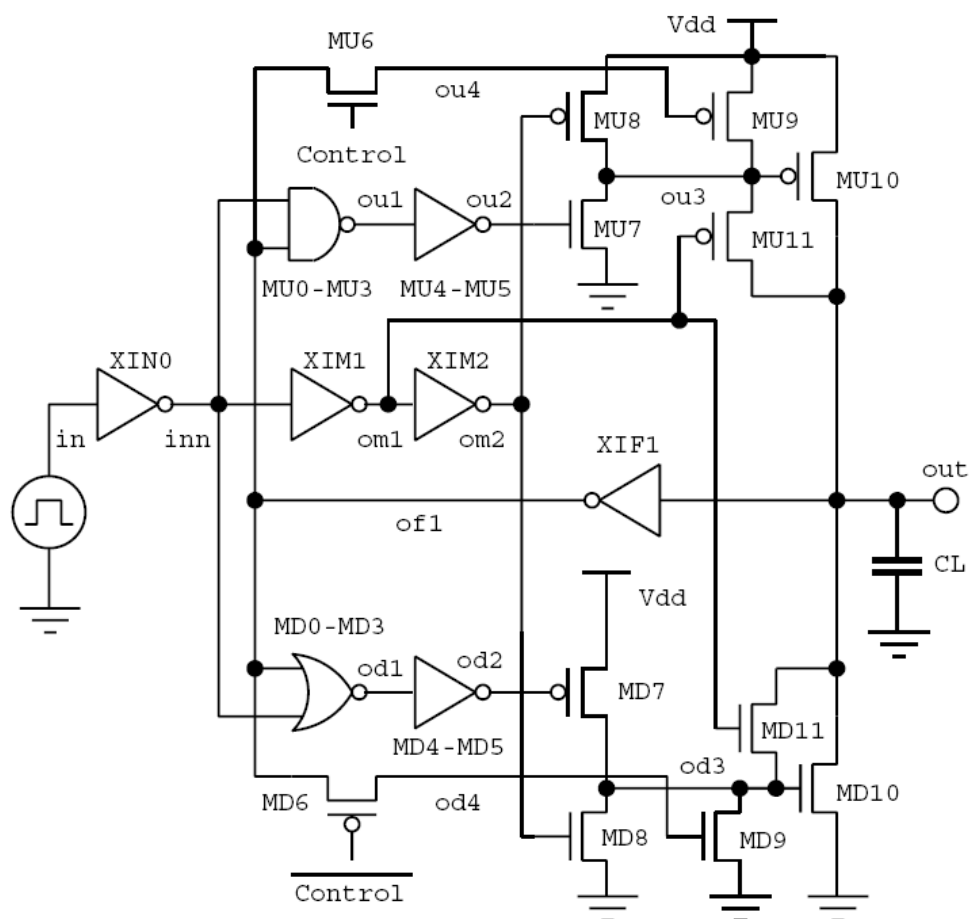
New line driver



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Provides both reduced voltage swing and pre-emphasis or full voltage swing

J.C.Garcia, J.A.Montiel, S.Nooshabadi
Adaptive Low/High Voltage Swing
CMOS Driver for On-Chip Interconnects
ISCAS 2007

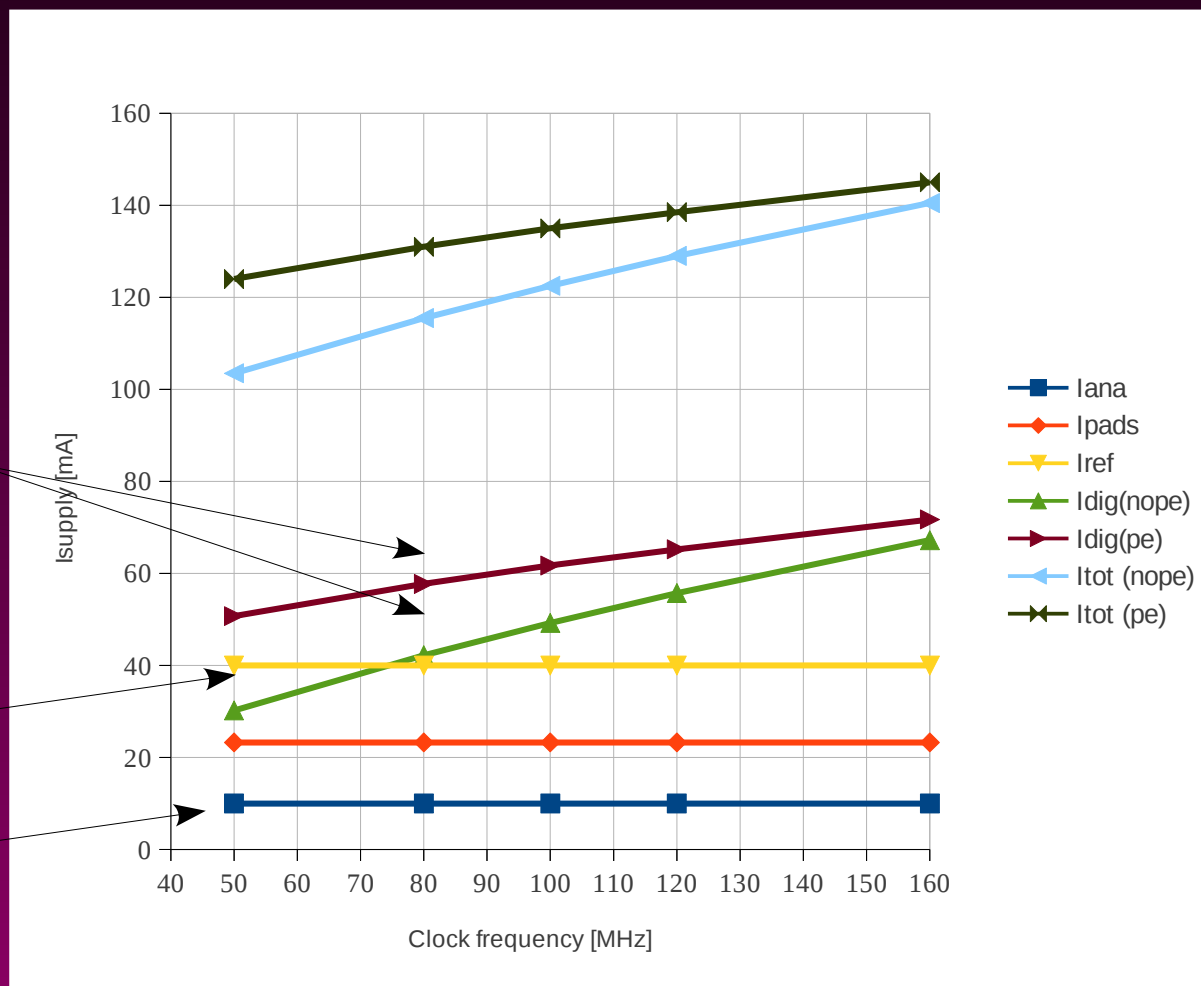




ToPiX v3 supply



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55% from the time stamp counter

Can be made almost negligible (zero in theory)

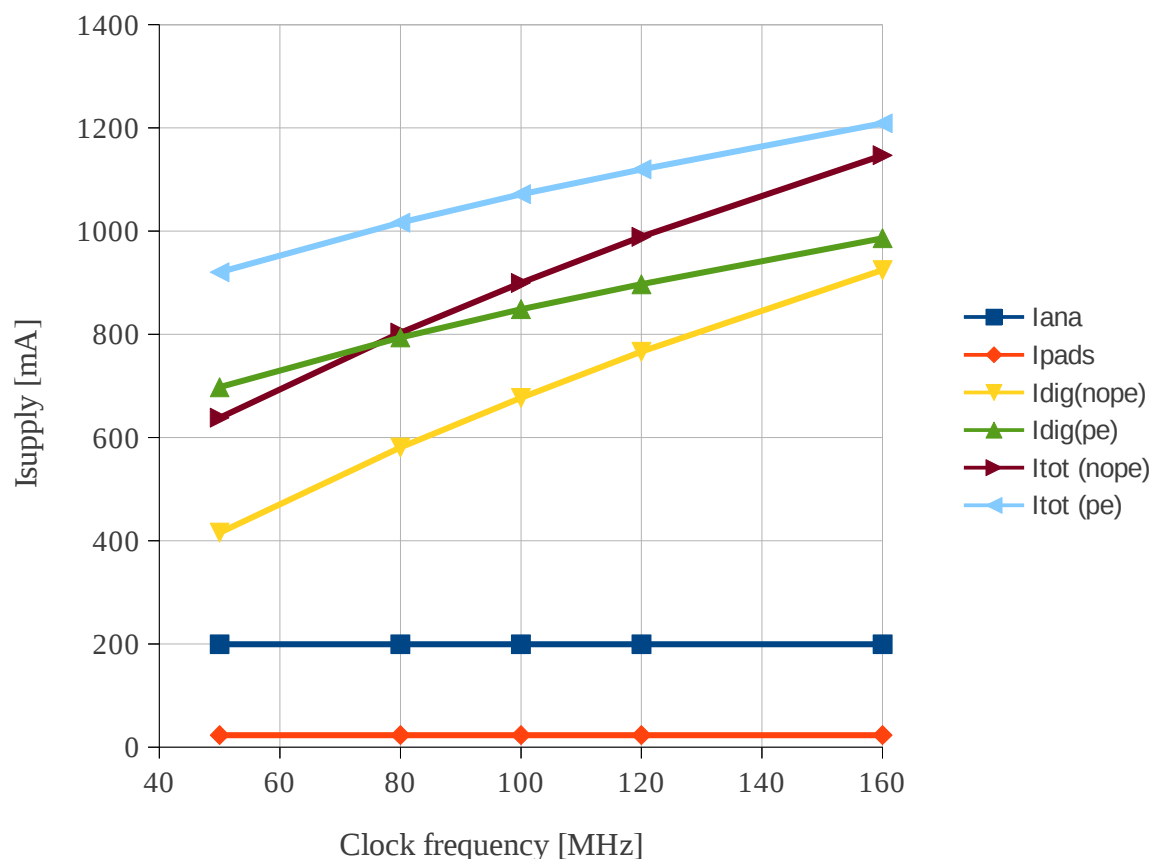
15 $\mu\text{A}/\text{pixel}$



Full chip estimate



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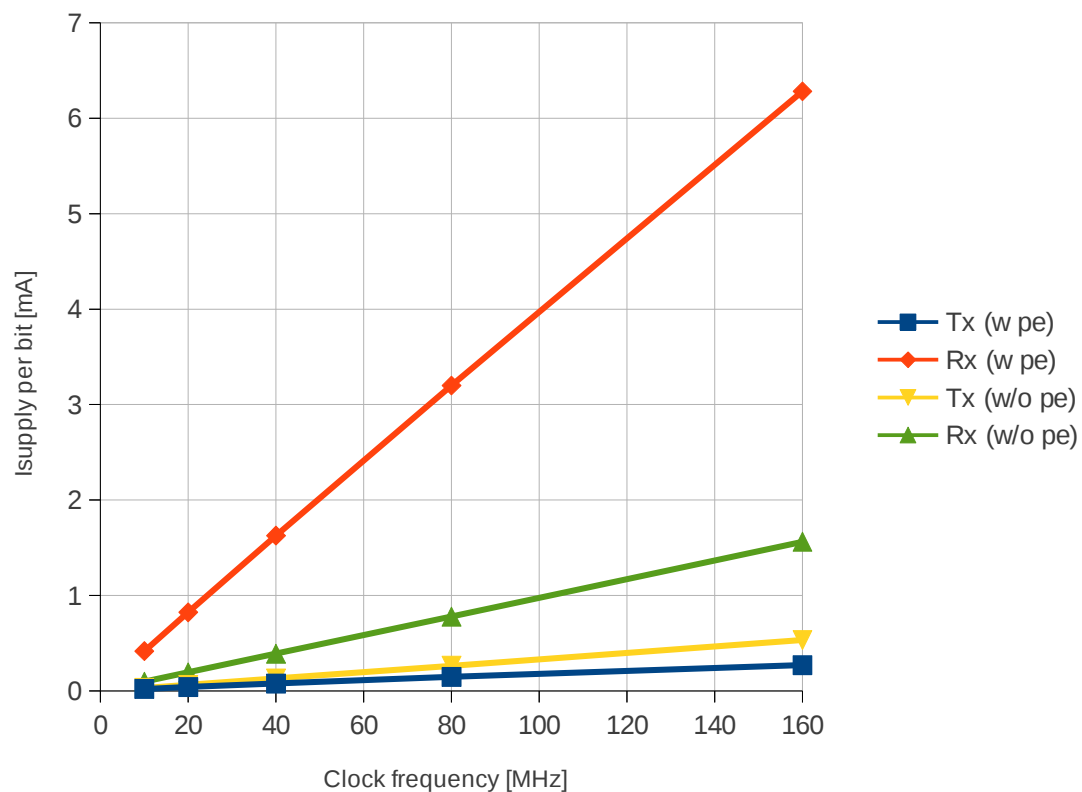
- * Very rough estimate
- * Still room for improvements (ToPiX v3 not really designed having low power in mind...)
- * Time stamp column drivers taken from NA62 GtkTo → room for improvement
- * However, power is dominated by digital logic, therefore it is $\propto f_{\text{clock}}$



v4 Tx-Rx simulations



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Simulations of the new driver and 128 receivers for different frequencies assuming Gray encoding.

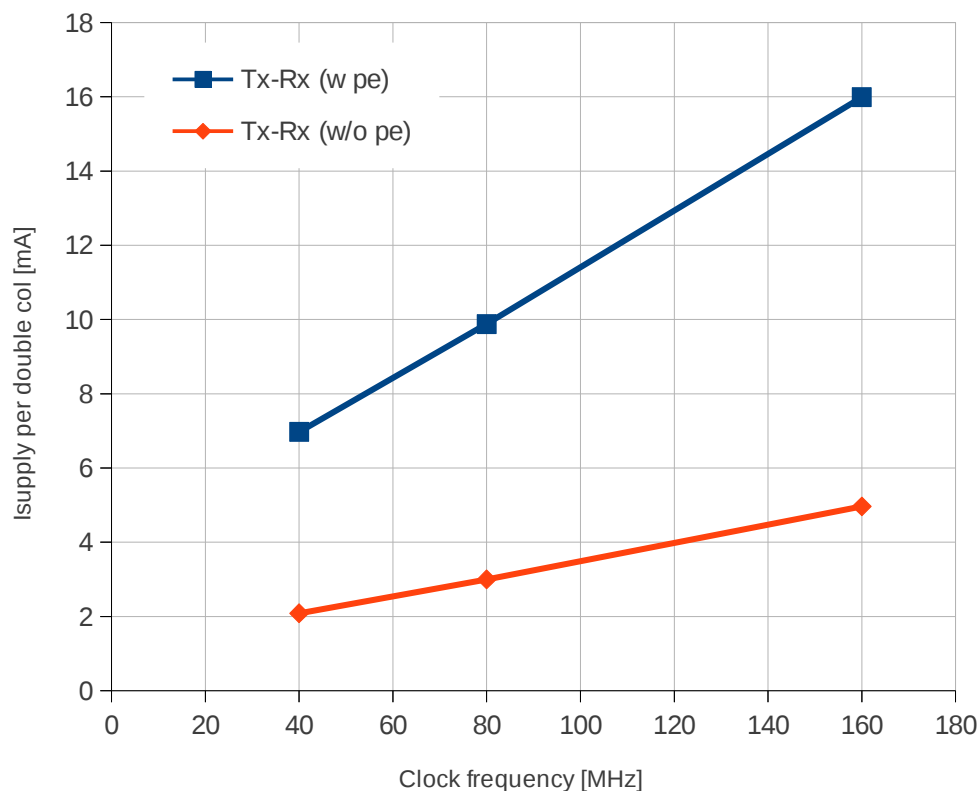
- * w pe : with reduced voltage swing and pre-emphasis
- * w/o pe : with full voltage swing and without pre-emphasis



Double column drivers current supply

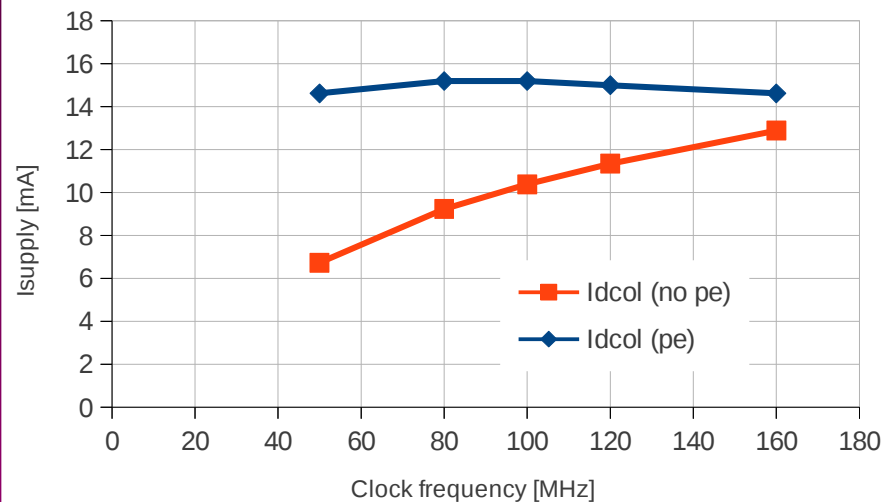


ToPiX v4 simulated



- * Power goes linearly with frequency
- * Reduced voltage swing reduces the driver power consumption but increases the power at the pixel receiver
- * Full swing looks a better solution unless a more efficient receiver architecture can be found

ToPiX v3 measured

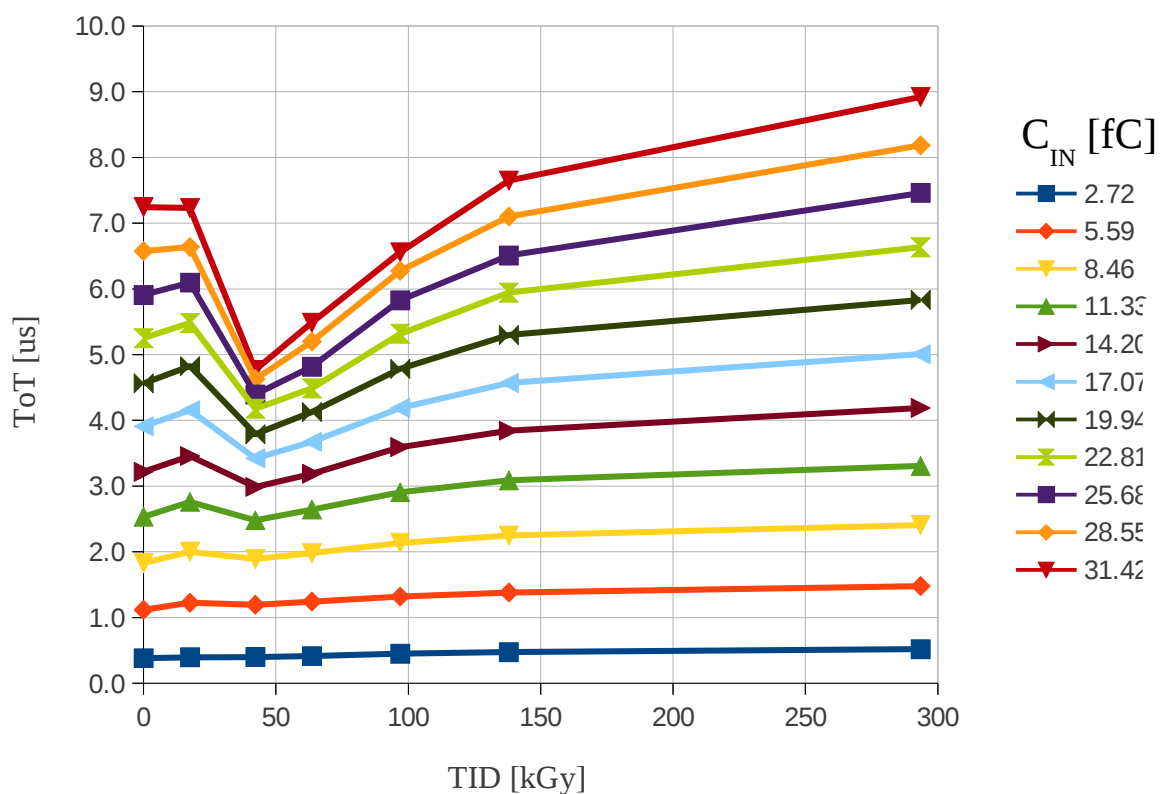




TID tests - ToT

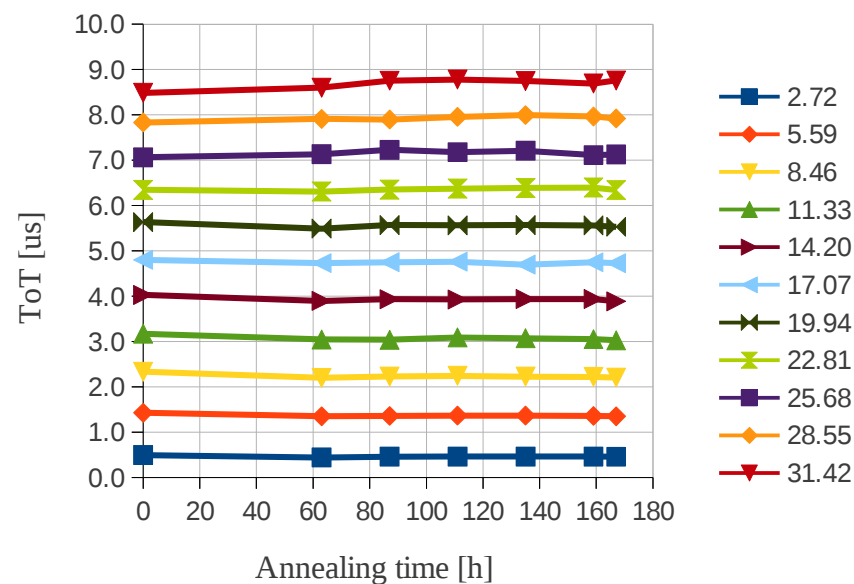


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During irradiation

Annealing @ 80 °C



Probably due to effects in the clipping circuit – enclosed layout required ?

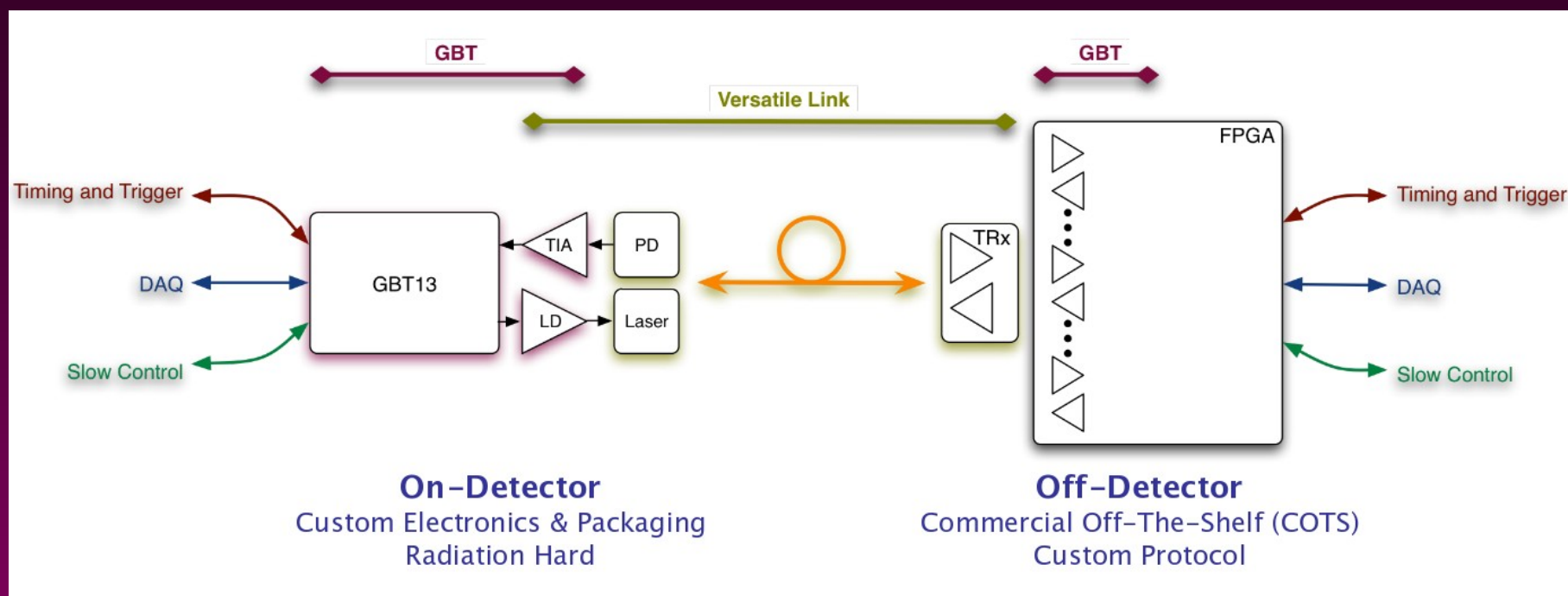


SEU tests



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- * SEU data from LNL beam test under analysis
- * Both ToPiX v3 and GBLD v4 have been irradiated
 - * Comparison of the two SEU protection schemes
- * First feeling : the SEU protection is not sufficient for the configuration register
- * Space constraints in the pixel cell lead to a very compact cell which is more sensitive to SEU even with triple redundancy
- * A new concept for the digital part of the pixel cell has to be found :
 - * Standard cells based layout with automatic synthesis (design time, SEU tolerance)
 - * Region of pixel concept (ATLAS FE-I4)

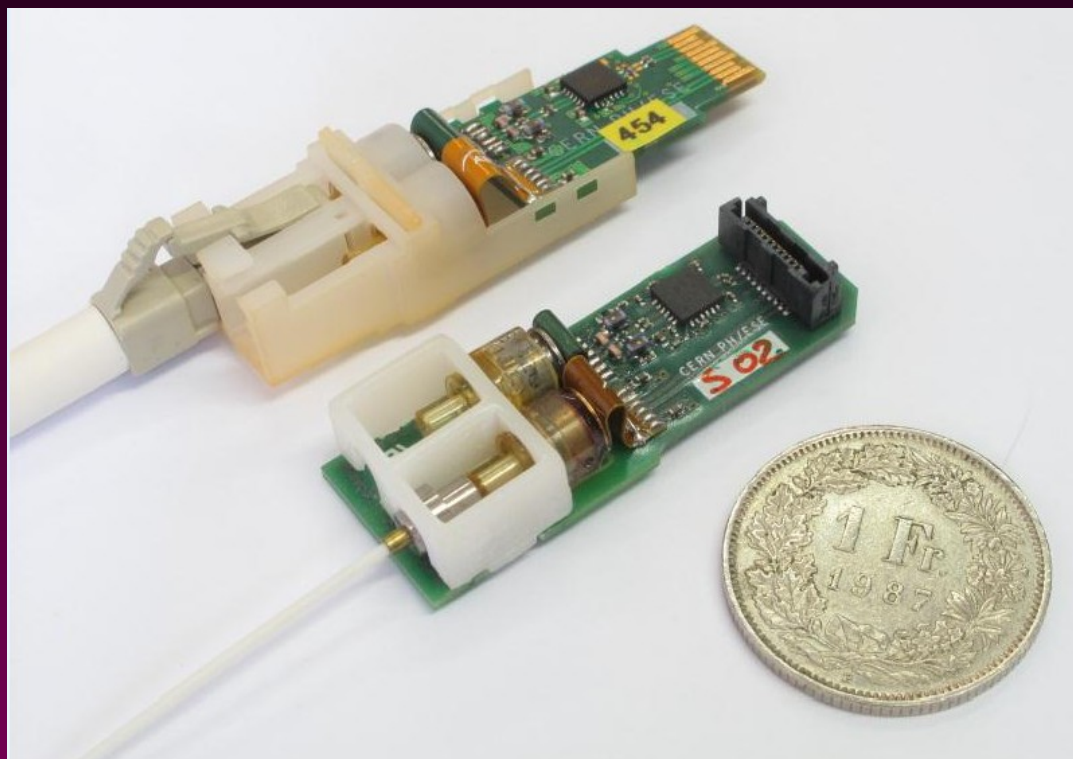




GBT components



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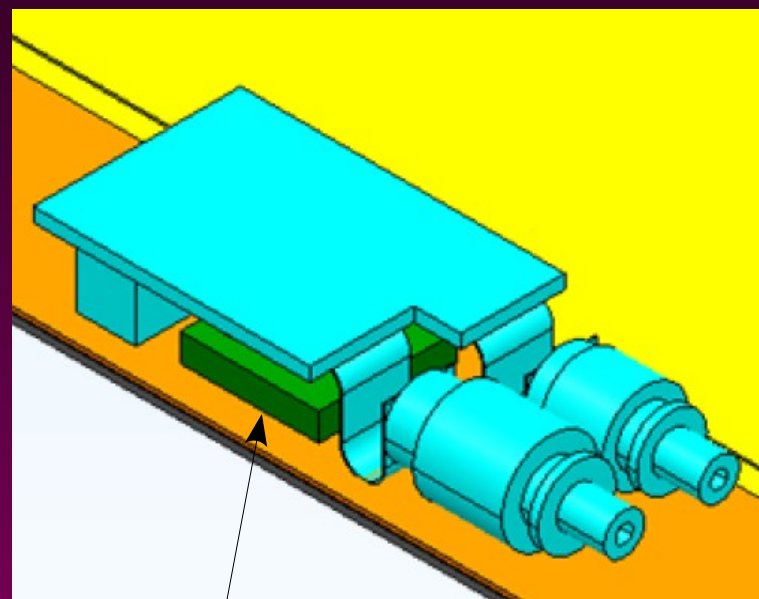
Versatile Transceiver

$50 \times 14 \times 10 \text{ mm}^3$

$45 \times 15 \times 8 \text{ mm}^3$

(F.Vasey, J.Troska, C.Soos)

Proposed arrangement
for CMS tracker (C.Soos)



GBTx $10 \times 10 \text{ mm}^2$
(P.Moreira et al.)

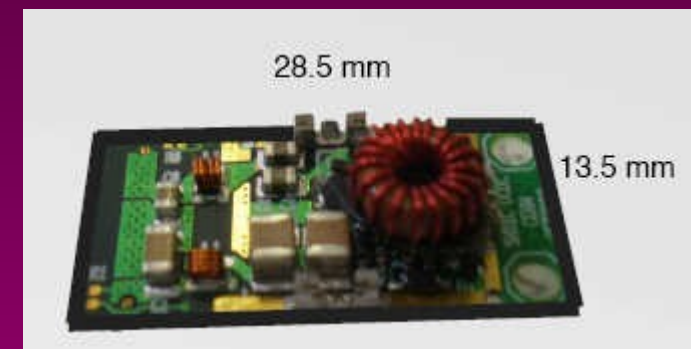


Power regulator



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- * ToPiX power supply $1.2 \text{ V} - I_{\text{DC}} \sim 1 \text{ A}$ (estimated)
→ *voltage drop on cables is not negligible*
- * A DC-DC converter solution compatible with the radiation levels and the magnetic field of a silicon tracker is under development @ CERN for sLHC
- * Current CERN version : $V_{\text{IN}} 10 \div 12 \text{ V}$, $V_{\text{OUT}} = 1.2 \div 3.3 \text{ V}$, $I_{\text{OUT}} < 3 \text{ A}$
- * $V_{\text{OUT}} = 1.5 \text{ V}$, $I_{\text{OUT}} < 3\text{-}4 \text{ A}$ now avail.
- * Board position t.b.d.
→ *ToPiX internal regulator t.b.d.*





Conclusions



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- * Developments on the ToPiX project show that the two critical trade-off:
 - ➔ Power consumption vs time resolution
 - ➔ SEU immunity vs pixel size
- * Decisions has to be taken on the time resolution and the SEU requirements in order to finalize the design
- * An on-chip voltage regulator will be probably mandatory
- * Cabling could be the real show-stopper